

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	655	((three two multiple plural) adj (step steps)) near3 (oxidation oxidiz\$3 oxidis\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 13:38
2	L8	79515	gate adj2 (insulat\$3 dielectric oxide dioxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 13:38
3	L15	13	4518630.urpn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 14:22
4	L22	2	4574466.URPN.	USPAT	2002/04/23 13:44
5	L23	72	1 and 8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 16:03
6	L30	6	4826779.URPN.	USPAT	2002/04/23 14:40
7	L31	388	(common commonly ordinary typical typically) near3 (heat\$3 near2 rate!)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 16:49
8	L38	11	31 same (si silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 16:54
9	L45	19	31 same (substrate wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 16:54
10	L52	25	38 45	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:02
11	L59	19659	(furnace oven) near15 (semiconductor wafer silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:03
12	L66	253002	temperature near2 control\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:04
13	L73	2161	59 and 66	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:04
14	L80	5815	(fast faster high higher) near4 (heat\$3 near2 rate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:06
15	L87	3824	(slower slow lower low) near4 (heat\$3 near2 rate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:07
16	L94	5765	(reduc\$3 varying variable varied decreas\$3 chang\$3 modulat\$3) near4 (heat\$3 near2 rate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:08
17	L108	391613	(reduc\$3 varying variable varied decreas\$3 chang\$3 modulat\$3) near4 (power potential wattage watts)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:09
18	L101	104	(80 87 94) and 73	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:50
19	L115	1	5688116.URPN.	USPAT	2002/04/23 17:43
20	L116	309	66 near15 59	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:50
21	L123	26	116 and (80 87 94 108)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/23 17:51
22	L130	1	"3392268".PN.	USPAT	2002/04/23 17:52
23	L134	1	"4300037".PN.	USPAT	2002/04/23 17:53
24	L135	1	"4323763".PN.	USPAT	2002/04/23 17:54